



## Product Information Sheet EPO-TEK® 301-2G

**Date:** September 2017  
**Rev:** IV  
**No. of Components:** Two  
**Mix Ratio by Weight:** 100 : 35  
**Specific Gravity:** Part A: 1.02      Part B: 0.89  
**Pot Life:** 8 Hours  
**Shelf Life- Bulk:** One year at room temperature

**Recommended Cure: 80°C / 3 Hours**

**Minimum Alternative Cure(s):**  
*May not achieve performance properties listed below*  
 23°C / 48 Hours

**NOTES:**

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- If product crystallizes in storage, place container in warm oven until crystallization disappears. Please refer to Tech Tip #7 on website.

**Product Description:** A two component version of EPO-TEK® 301-2 with added indicator for enhanced process control capabilities.

**Typical Properties:** Cure condition: varies as required      Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Clear/colorless	Part B: Clear/colorless	
* Consistency:	Pourable liquid		
* Viscosity (23°C) @ 100 rpm:	225 - 425	cPs	
Thixotropic Index:	N/A		
* Glass Transition Temp:	≥ 80	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	61	x 10 <sup>-6</sup> in/in°C
	Above Tg:	180	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	80		
Lap Shear @ 23°C:	> 2,000	psi	
Die Shear @ 23°C:	≥ 15	Kg	5,334 psi
Degradation Temp:	360 °C		
Weight Loss:			
	@ 200°C:	0.01	%
	@ 250°C:	0.46	%
	@ 300°C:	2.19	%
Suggested Operating Temperature:	< 300 °C (Intermittent)		
Storage Modulus:	298,719	psi	
* Particle Size:	≤ 20	microns	
ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	N/A		
Volume Resistivity @ 23°C:	≥ 4 x 10 <sup>12</sup>	Ohm-cm	
Dielectric Constant (1KHz):	4.34		
Dissipation Factor (1KHz):	0.031		
OPTICAL PROPERTIES @ 23°C:			
Spectral Transmission:	> 98% @ 440-1440	nm	
Refractive Index:	1.5323 @ 589	nm	

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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